

# POSSIBLE LASER TARGET FABRICATION AT THE ION BEAM CENTER (IBC)

Jürgen Fassbender

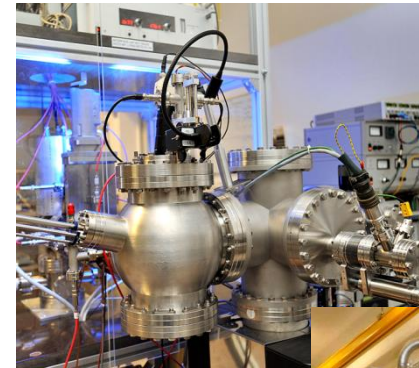
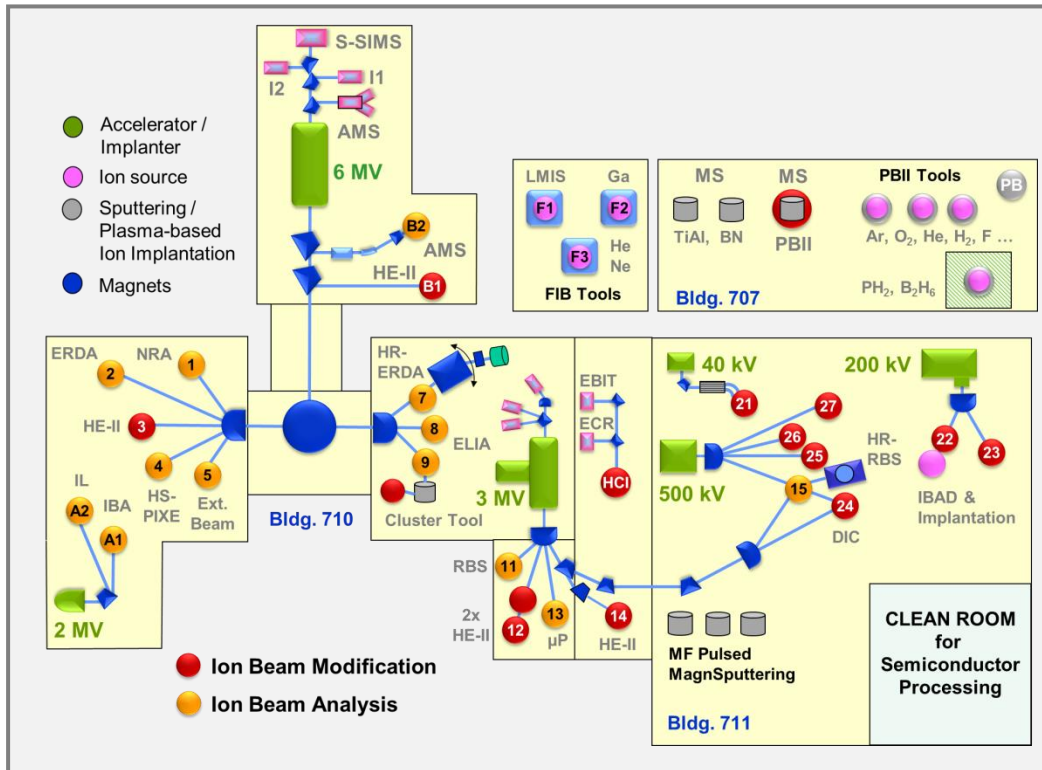
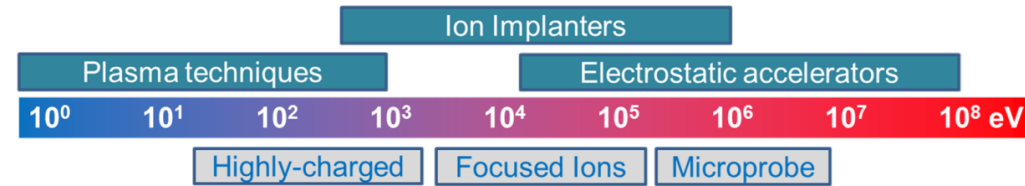
Institute of Ion Beam Physics and Materials Research



# Motivation and Mission of the Institute of Ion Beam Physics and Materials Research

- Fabrication and investigation of **nanostructured systems** with special **electronic, optic** and **magnetic** properties.
- Investigation of materials for future **information technology**
- Applications in **micro/nanoelectronics** and **optoelectronics**, **magnetic storage**, etc.
- Use of three large scale facilities of the HZDR:
  - **Ion Beam Centre (5 eV - 50 MeV)**
  - Radiation Source ELBE (free electron laser,  $\lambda = 3 - 280 \mu\text{m}$ )
  - High Magnetic Fields Laboratory (up to 90 T)

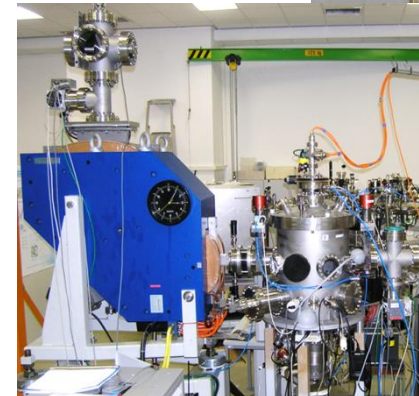
# Versatile facilities and instrumentation for materials modification and analysis with ions



**SNIPER Tool**  
for single ion  
implantation



**High-energy  
implantation  
endstation**



**Magnetic Spectr.**  
for high-resolution  
RBS



**6 MV Tandem  
Accelerator**



# In addition within IBC: Nanofabrication and Analysis Techniques



**Lithography**

**Wet Chemistry**



**Etching**

**Deposition**



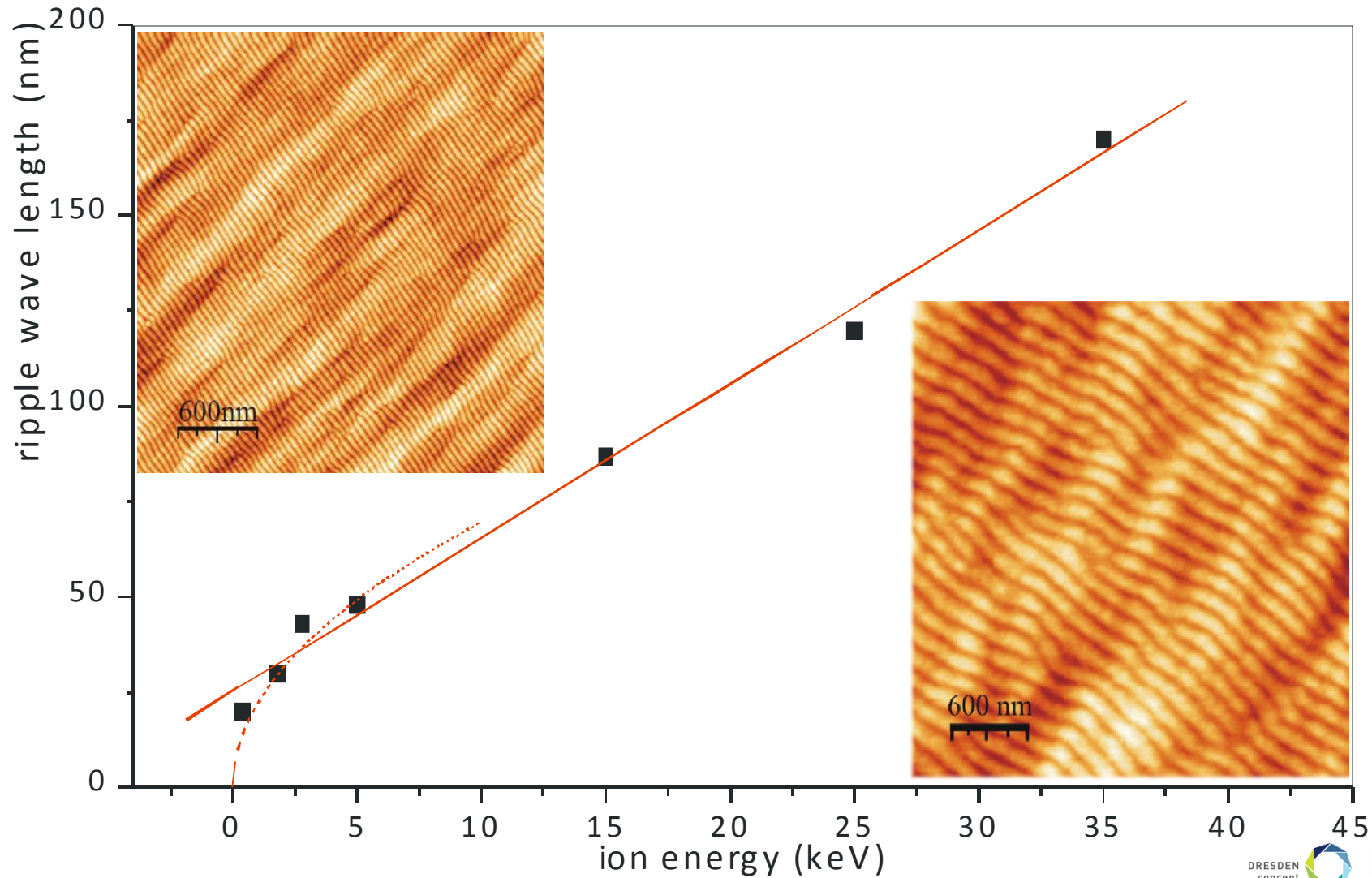
**Electron  
Microscopy**



**Lab-based  
x-ray  
techniques**

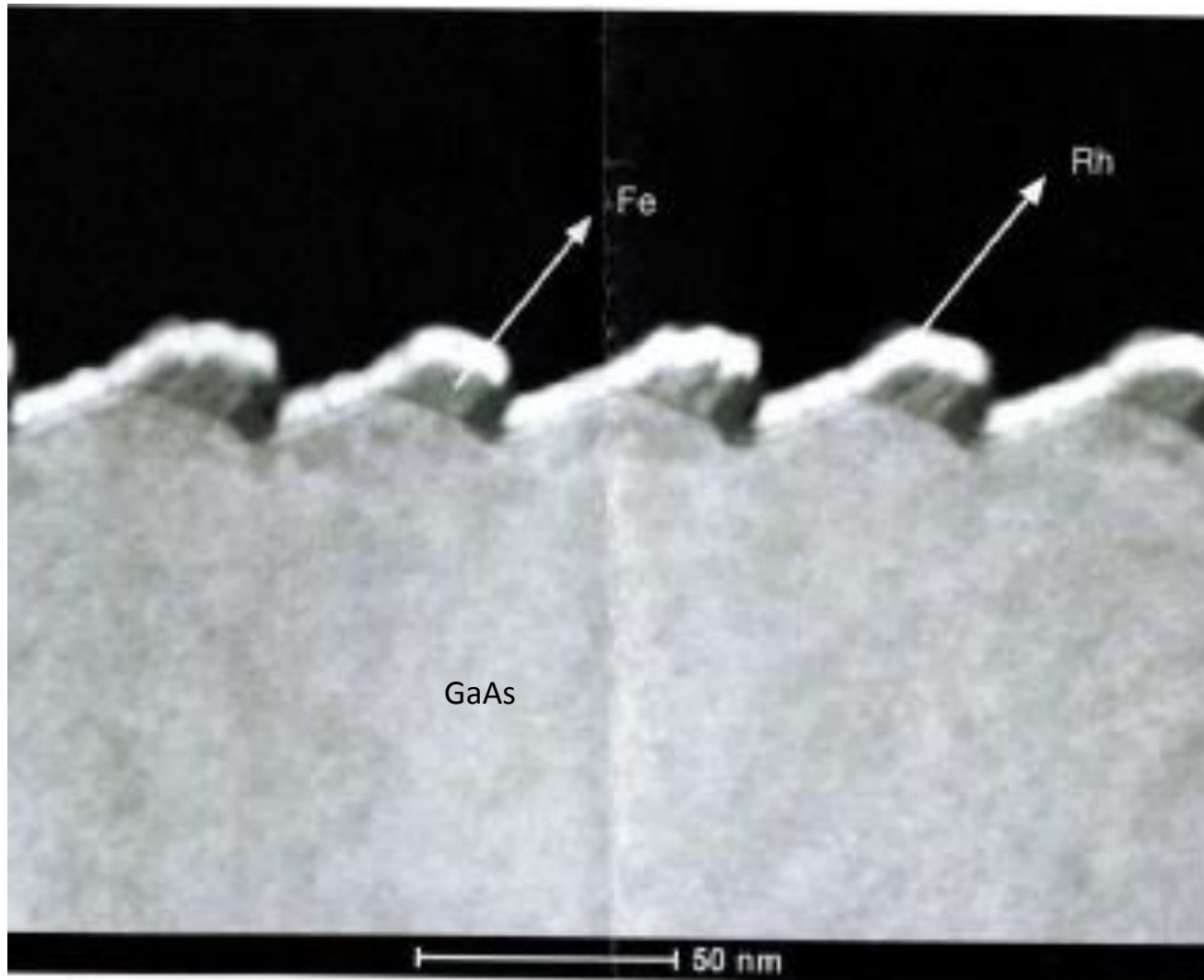
# Examples of nanofabricated structures

# Ripple structures due to ion erosion (self-organization)



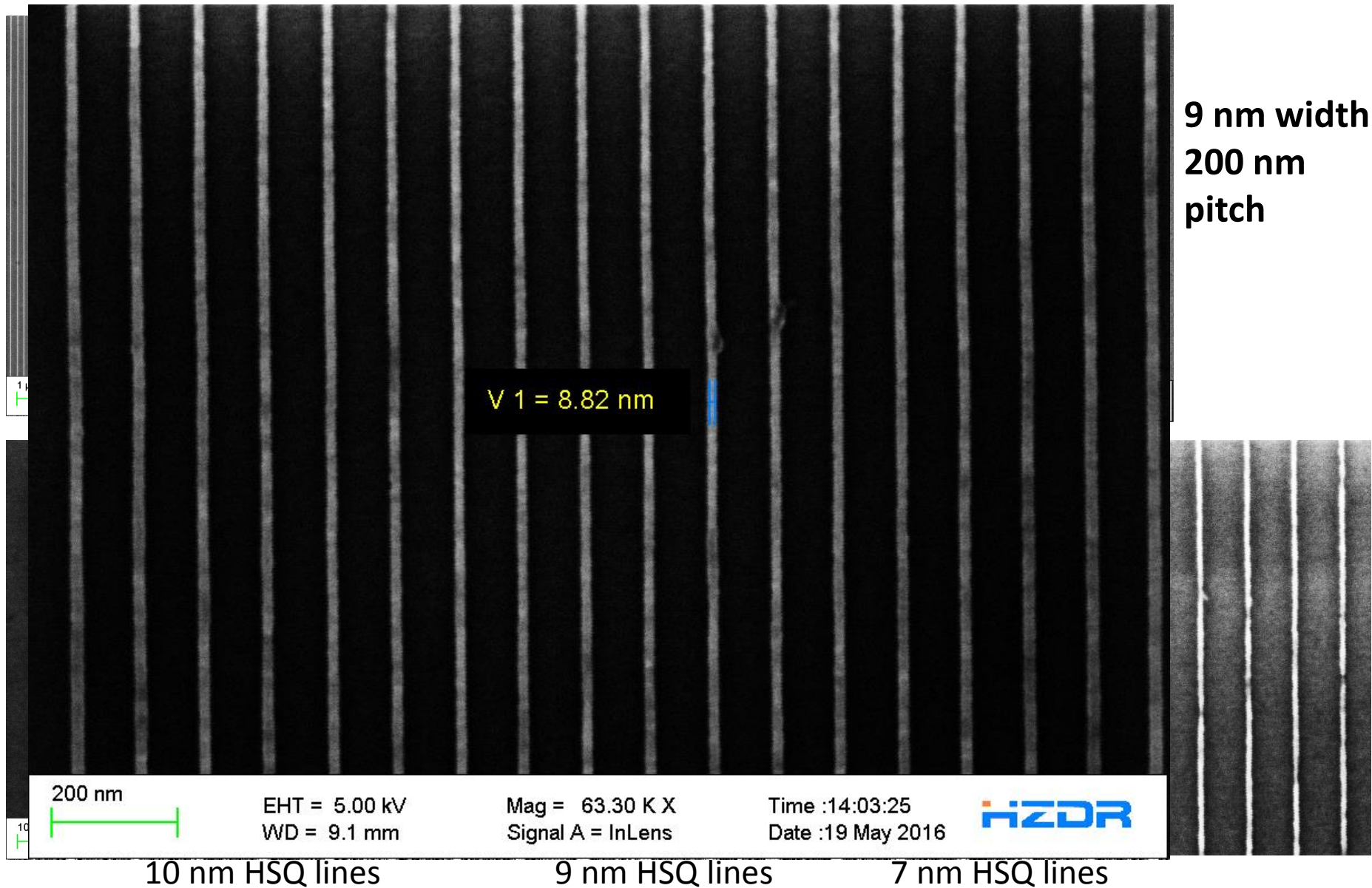
# Nanowires on ripple structures

## Cross-section TEM



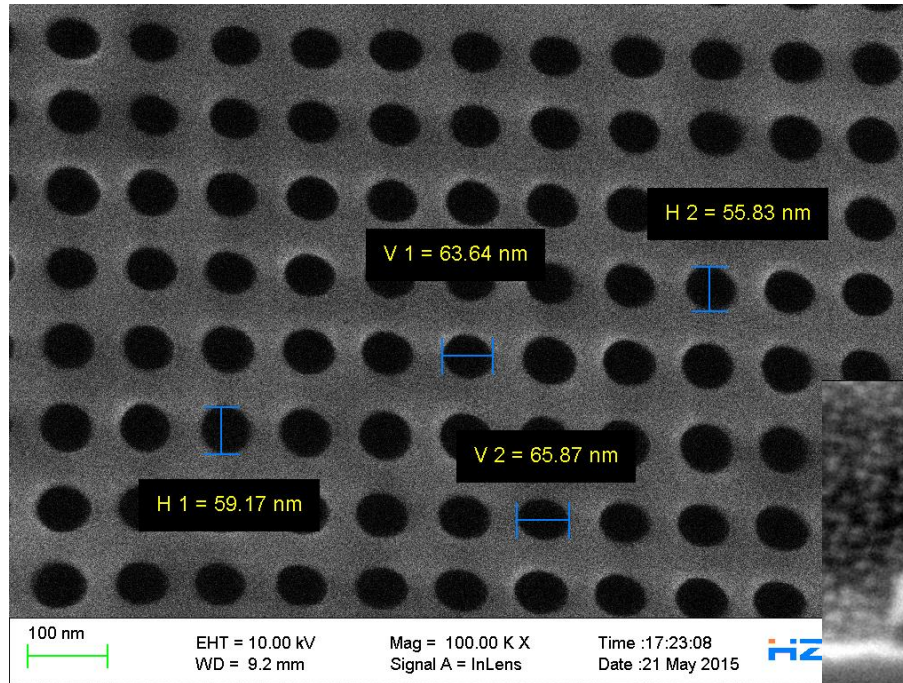


# Electron lithography of lines

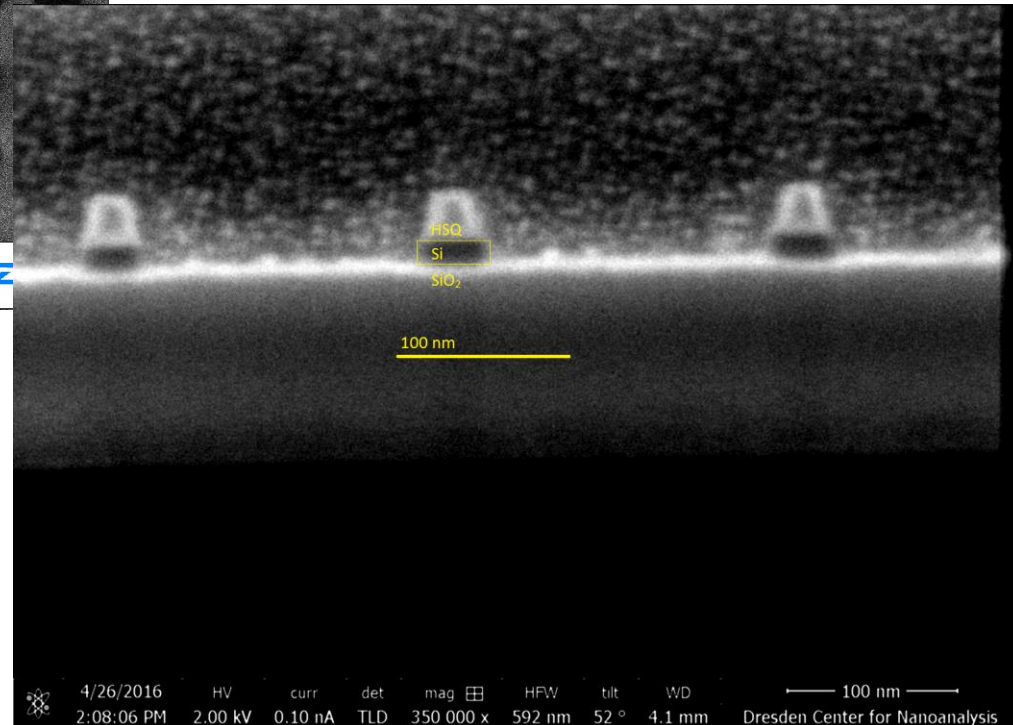




# Lithographic nanofabrication



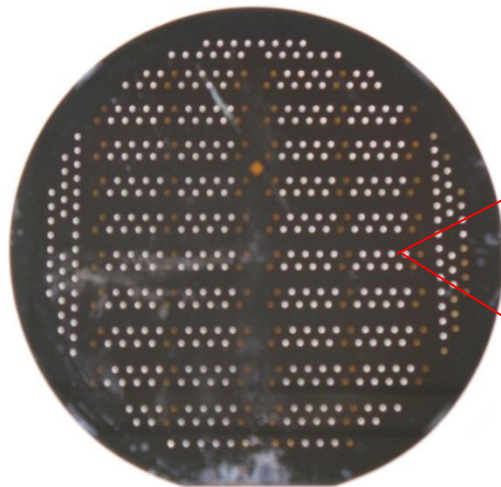
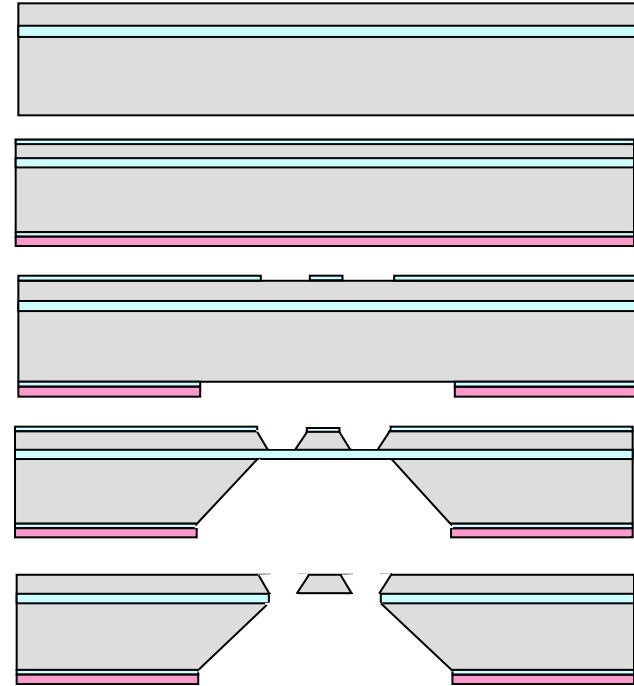
Array of Pt nanodots



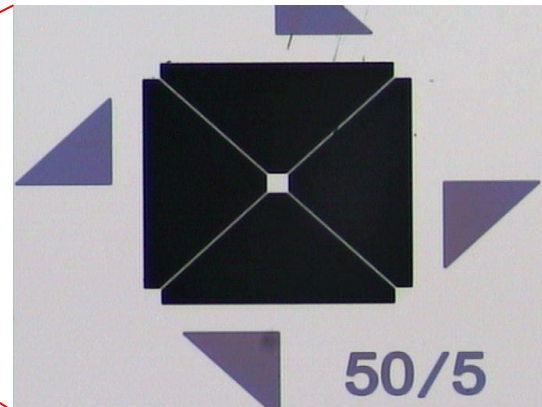
Si nano-structures

# Silicon micromachining for reduced mass targets

- silicon substrate (usually SOI)
- thermal oxydation & LPCVD  $\text{Si}_3\text{N}_4$  deposition
- photolithographic patterning on both sides
- deep etching (wet on back side and dry plasma on front side)
- buried oxide removing



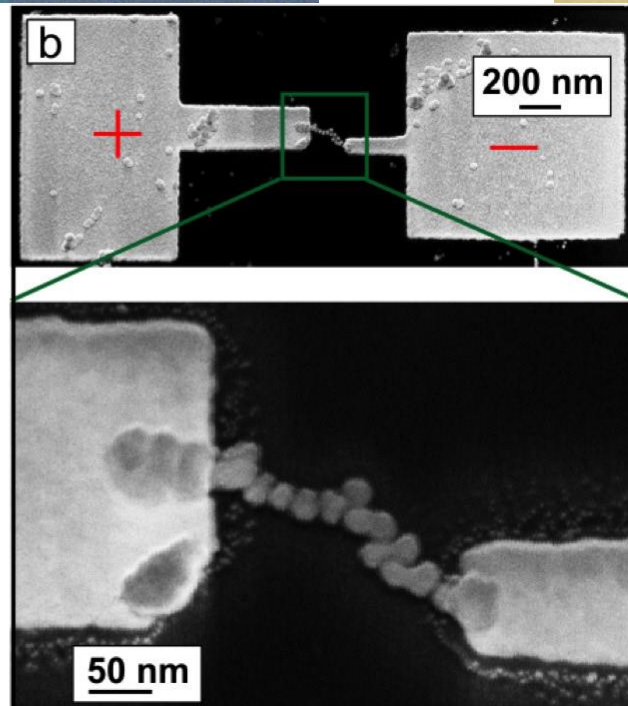
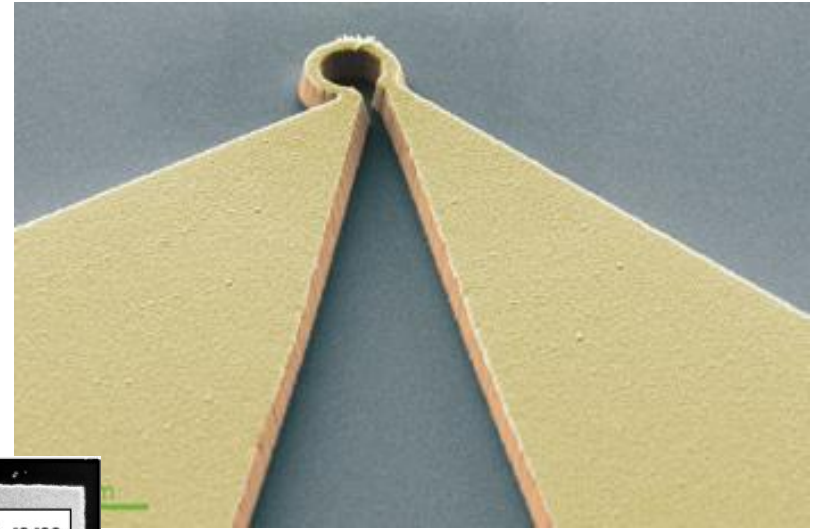
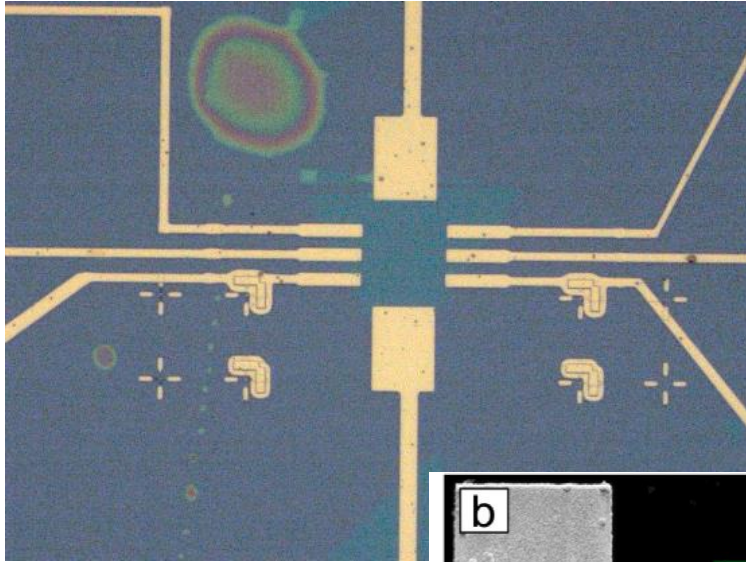
Processed 100 mm SOI wafer



central target:  
area  $50 \times 50 \mu\text{m}$ ,  
thickness  $2 \mu\text{m}$

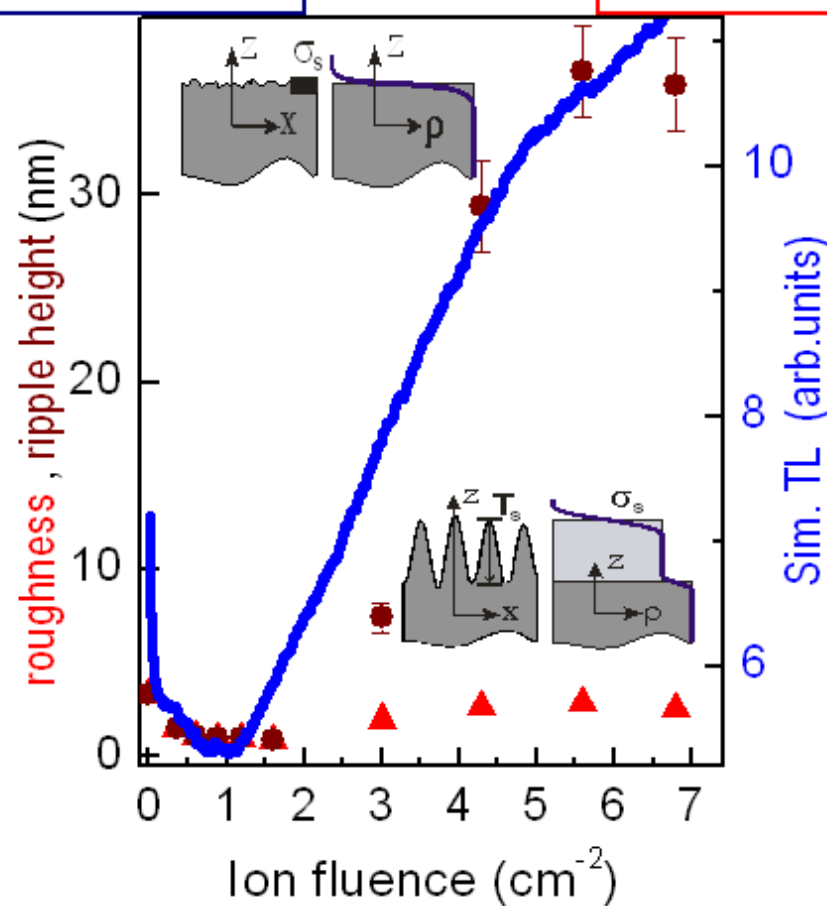
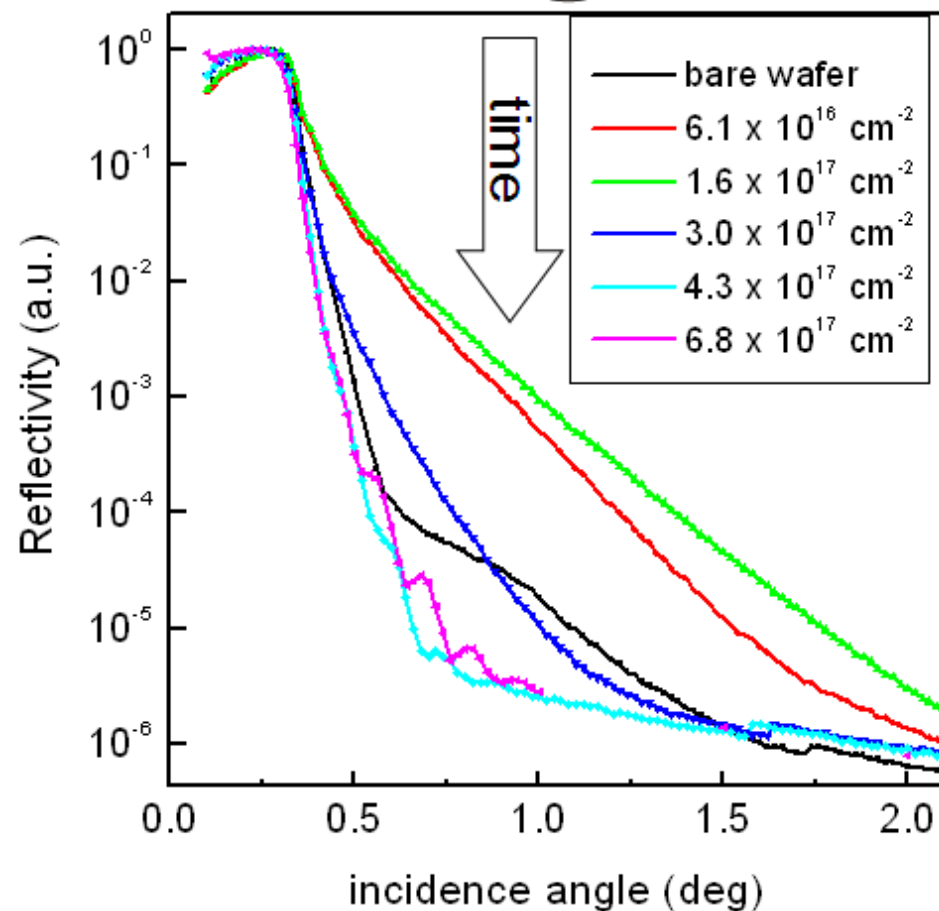
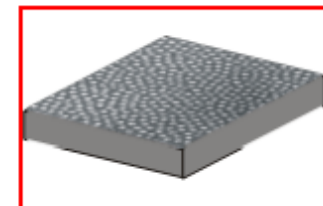
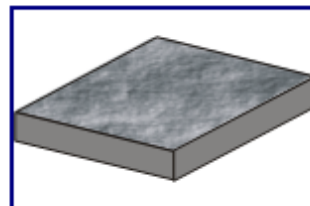
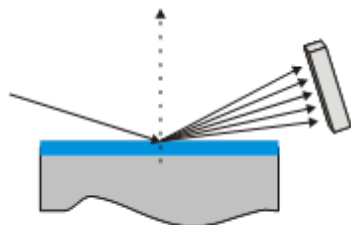
supporting beam  
dimensions  
 $w \times t = 5 \times 2 \mu\text{m}$

# Electrical wiring and contacting

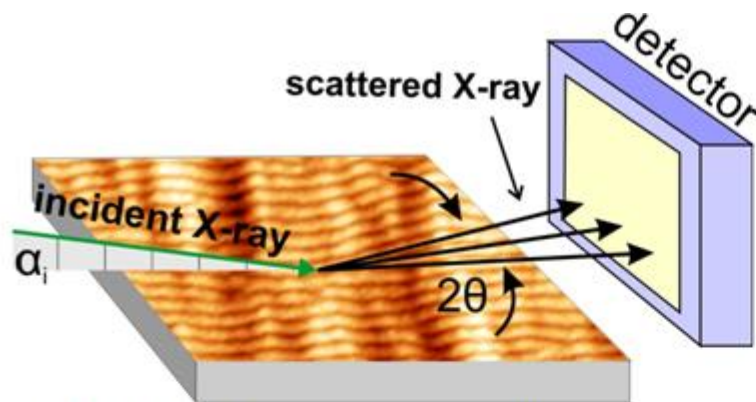


# Structural Characterization





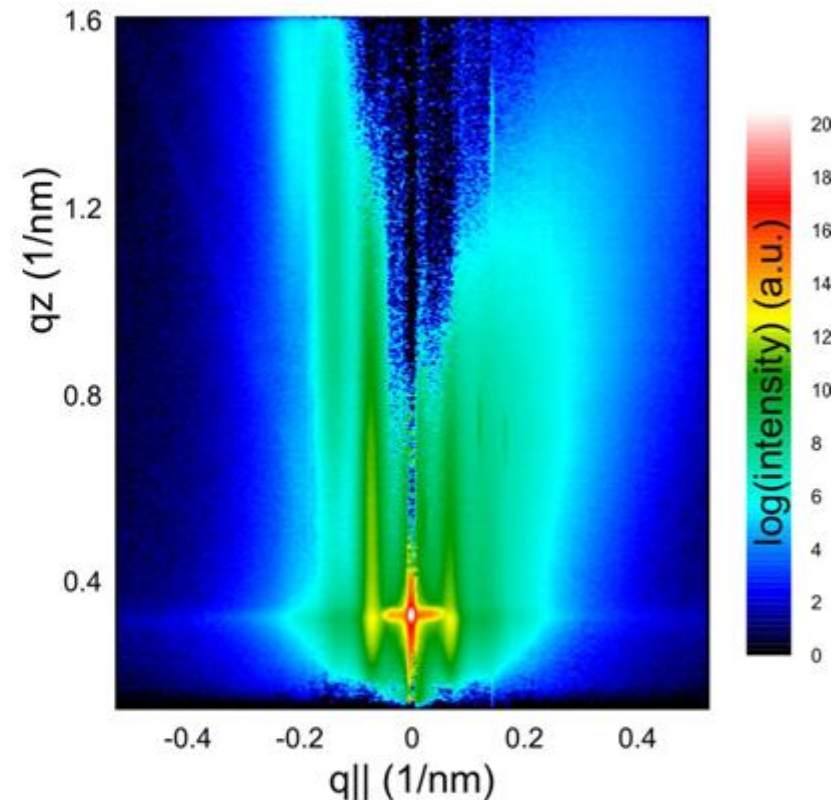
A. Keller, A. Biermanns, G. Carbone, J. Grenzer, S. Facsko, O. Plantevin, R. Gago, and T. H. Metzger, APL 94, 193103 (2009).



GISAXS measurements:

- Satellite peaks indicating ordered ripples
- Peak position and width related to ripple wavelength and ordering
- Asymmetric facet streaks indicating asymmetric ripple shape

Measurements GISAXS



more GID & Si: A. Biermanns et al., J. OF APPLIED PHYSICS, 104(20), (2009).

# IBC Team

